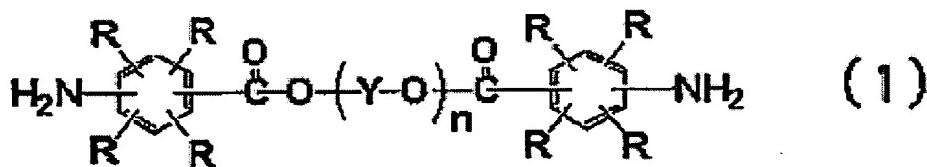


**AMENDMENTS TO THE CLAIMS:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

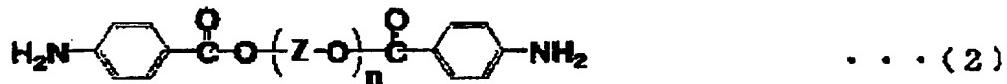
**LISTING OF CLAIMS:**

1. (Currently Amended) An adhesive resin composition comprising:  
a thermoplastic polyimide obtained by reacting a diamine component comprising a diamine represented by the following general formula (1) with a tetracarboxylic acid dianhydride, and  
a thermosetting resin contained in the ratio of from 1 to 200 weight parts, based on 100 weight parts of the thermoplastic polyimide,



wherein, in the formula (1), Rs are each independently an atom or a group selected from a-the group comprising consisting of a hydrogen atom, a halogen atom and a hydrocarbon group; n is a positive number of 1 to 50 on an average; Y represents an unsubstituted or substituted divalent organic alkylene group having 2 to 10 carbons or an alkyl ether group having 2 to 10 carbons; and Ys may be the same or different when n is not less than 2.

2. (Currently Amended) The adhesive resin composition according to claim 1, wherein the diamine represented by the ~~general~~-formula (1) is a diamine represented by the following ~~general~~ formula (2),



wherein, in the formula (2), n is an integer of 1 to 50 on an average; Z represents an alkylene group having 2 to 10 carbons; Zs may be the same or different when n is not less than 2.

3. (Currently Amended) The adhesive resin composition according to claim 1, wherein the diamine represented by the ~~general~~-formula (1) is contained in the amount of not less than 20 mole % in the total diamine components.

4. (Previously Presented) An adhesive in the form of a film comprising the adhesive resin composition as claimed in claim 3.

5. (Original) A semiconductor device with semiconductor elements attached using the adhesive in the form of a film as claimed in claim 4.

6. (Previously Presented) An adhesive in the form of a film comprising the adhesive resin composition as claimed in claim 2.

7. (Previously Presented) A semiconductor device with semiconductor elements attached using the adhesive in the form of a film as claimed in claim 6.

8. (Previously Presented) An adhesive in the form of a film comprising the adhesive resin composition as claimed in claim 1.

9. (Previously Presented) A semiconductor device with semiconductor elements attached using the adhesive in the form of a film as claimed in claim 8.